

PRODUCT DATA SHEET

5RMA-RC

Liquid Flux

Introduction

5RMA-RC is a heat-stabilized rosin flux designed for soldering with preforms or wire. It is formulated for use with a wide range of temperatures and metallizations. **5RMA-RC** is a low-voiding formula designed to improve wetting performance and reduce process variability.

5RMA-RC is a no-clean, mildly activated flux. It is compatible with Pb-free alloys, pure In, and In-containing alloys, as well as with high-Pb and SnPb alloys.

Cleaning

5RMA-RC is a no-clean flux. Removal of post-reflow flux residue is usually not necessary. If cleaning is desired, commercially available flux residue removers can be used.

Packaging

Standard packaging for **5RMA-RC** is 1 U.S. pint (0.473 liter) and 1 U.S. gallon (3.785 liters).

| Properties | 5RMA-RC Flux | Test Method |
|------------------------------------|--------------------------|---|
| Flux Type | ROL1 | J-STD-004 |
| Application Technique | Spray, dip, spin coating | |
| Specific Gravity | 0.86 | |
| Typical Viscosity | 2–10cSt | Brookfield viscometer or Zahn Cup |
| SIR Testing | Pass | J-STD-004 |
| Typical Acid Value | ~38mg KOH/g | Titration |
| Shelf Life at 0–30°C | 3 years | Viscosity change/microscope examination |
| Typical Post-Reflow Residue Weight | 27% | TGA data post-reflow residue |

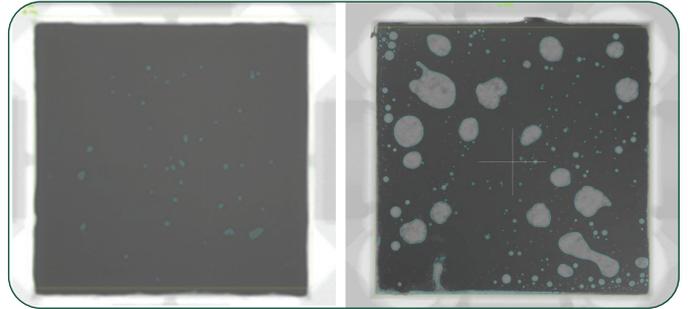
*All information is for reference only.
Not to be used as incoming product specifications.*

Storage and Handling

The shelf life of **5RMA-RC** is 3 years when stored at 0–30°C. Flux should be allowed to reach ambient temperature prior to use. Containers should be labeled with date and time of opening.

Solder Thermal Interface Material (sTIM) Applications

Void X-ray images on an indium preform:



5RMA-RC (Typically <3%)

Competition

Technical Support

Indium Corporation sets the industry standard in providing rapid response, onsite technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

Safety Data Sheets

The SDS for this product is available by contacting askus@indium.com

Recommended Application Notes

- *Flux and Solder Compatibility* (Form No. 97751)
- *Common Elements* (Form No. 98557)
- *Pb-Free Solder FAQs* (Form No. 97758)
- *Practical Suggestions for Preform Design* (Form No. 97763)

Other Recommended Products

- Solder preforms
- Solder wire
- Solder research kits

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

*All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.
Indium Corporation is an ISO 9001:2015 registered company.*

From One Engineer To Another®

Contact our engineers: askus@indium.com

Learn more: www.indium.com



Form No. 100404 (A4) R1

ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900



©2025 Indium Corporation